

# **SPECIFICATIONS**

#### **Mechanical**

Durability: 30 Cycles Min.

Socket Retention Force: 65g/Pin. Min.
CHIP INSERTION FORCE: 7kgMax
CHIP EXTRACTION FORCE: 5kgMax
SOLDER BALL SHEAR FORCE: 750q Min

# **Electrical**

Contact Resistance: 30mW Max.

Dielectric Withstanding Voltage: 500V

Insulation Resistance: 800MW min.

## **Physical**

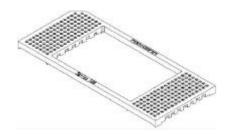
**Base:** Thermoplastic, UL 94V-0 rated, Black Color **Cap:** Thermoplastic, UL 94V-0 rated, Black Color

Contact: Copper Alloy

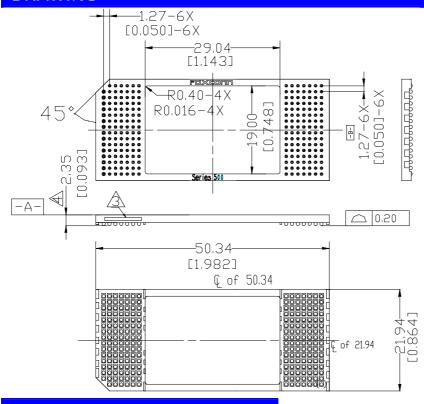
Plating: See "ORDERING INFORMATION"
Operating Temperature: -55°C to +110°C

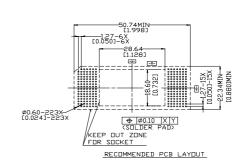
## **LIF/BGA 223 SOCKET**

BGA Series CPU Socket Vertical, SMT Type 1.27 mm [.05"] Pitch 223Pos.



## **DRAWING**





# ORDERING INFORMATION

